



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant:	Daniel Yap)	Group Art No.:	2827
Application No:	10/053,159)	Examiner:	Thai, Luan C.
Filed:	1/15/2002)	Re: RESPONSE	
For:	"Precision Electroplated Solder Bumps..."))	Our Ref: B-3752DIV 619413-2	
)	Date: June 18, 2003	

Commissioner for Patents
POB 1450
Alexandria, VA 22313-1450

Amendment

Dear Sir:

This paper is filed in response to the official action dated March 18, 2003.

Amendments to the specification can be found on page 2 of this paper.

Amendments to the abstract can be found on page 3 of this paper.

Amendments to the claims begin on page 4 of this paper.

The Remarks section begins on page 8 of this paper.